

No. : 5/LOA/ICoMPAC/2017
Subject : Official Letter of Acceptance

Dear **Witantyo David Setyawan and David Setyawan.**

On behalf of the Committee of International Conference on Mathematics: Pure, Applied and Computation, ICoMPAC 2017, we are pleased to inform you that your paper “**Enhancement of Efficiency and Reduction of Grid Thickness Variation on Casting Process with Lean Six Sigma Method**“ has been accepted to be presented in the conference.

We hope that you would be able to attend the conference that will be held by Mathematics Department, Institut Teknologi Sepuluh Nopember, Surabaya.

Should you have any enquiries and questions, please email us at icompac@its.ac.id while for more detailed information, please find it in our website <http://www.icompac.its.ac.id/>.

We look forward to your contribution at Surabaya.

Best Regards,
Conference Chairman



Dr. Dra. Mardijah, MT
NIP. 19670114 199102 2 001



M **MATHEMATICS DEPARTMENT**

Institut Teknologi Sepuluh Nopember Surabaya

Kampus ITS Sukolilo, Surabaya 60111, Indonesia

Telp: +62315943354; Fax: +62315996506; Url: <http://www.icompac.its.ac.id>